United States Patent [19]

Jones et al.

[11] **Des. 271,197**

[45] ** **Nov. 1, 1983**

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[54] **COMBINED INTEGRATED CIRCUIT PACKAGE CARRIER AND SOCKET ASSEMBLY**

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[73] Assignee: **Robinson-Nugent, Inc.**, New Albany, Ind.

[**] Term: **14 Years**

[21] Appl. No.: **236,795**

[22] Filed: **Feb. 23, 1981**

[51] **Int. Cl.** .... **D13—03**
[52] **U.S. Cl.** **D13/24**
[58] **Field of Search** .... D13/12, 24, 99; 361/403, 412, 415; 339/18 R, 18 B, 17 C, 17 M, 75 MF, 176; 206/335; D9/414, 424, 456

[56] **References Cited**

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[57] **CLAIM**

The ornamental design for a combined integrated circuit package carrier and socket assembly, as shown and described.

DESCRIPTION

FIG. 1 is a top plan view of a combined integrated circuit package carrier and socket assembly, showing our new design.

FIG. 2 is a left side elevational view thereof on a reduced scale.

FIG. 3 is a bottom plan view thereof on a reduced scale.

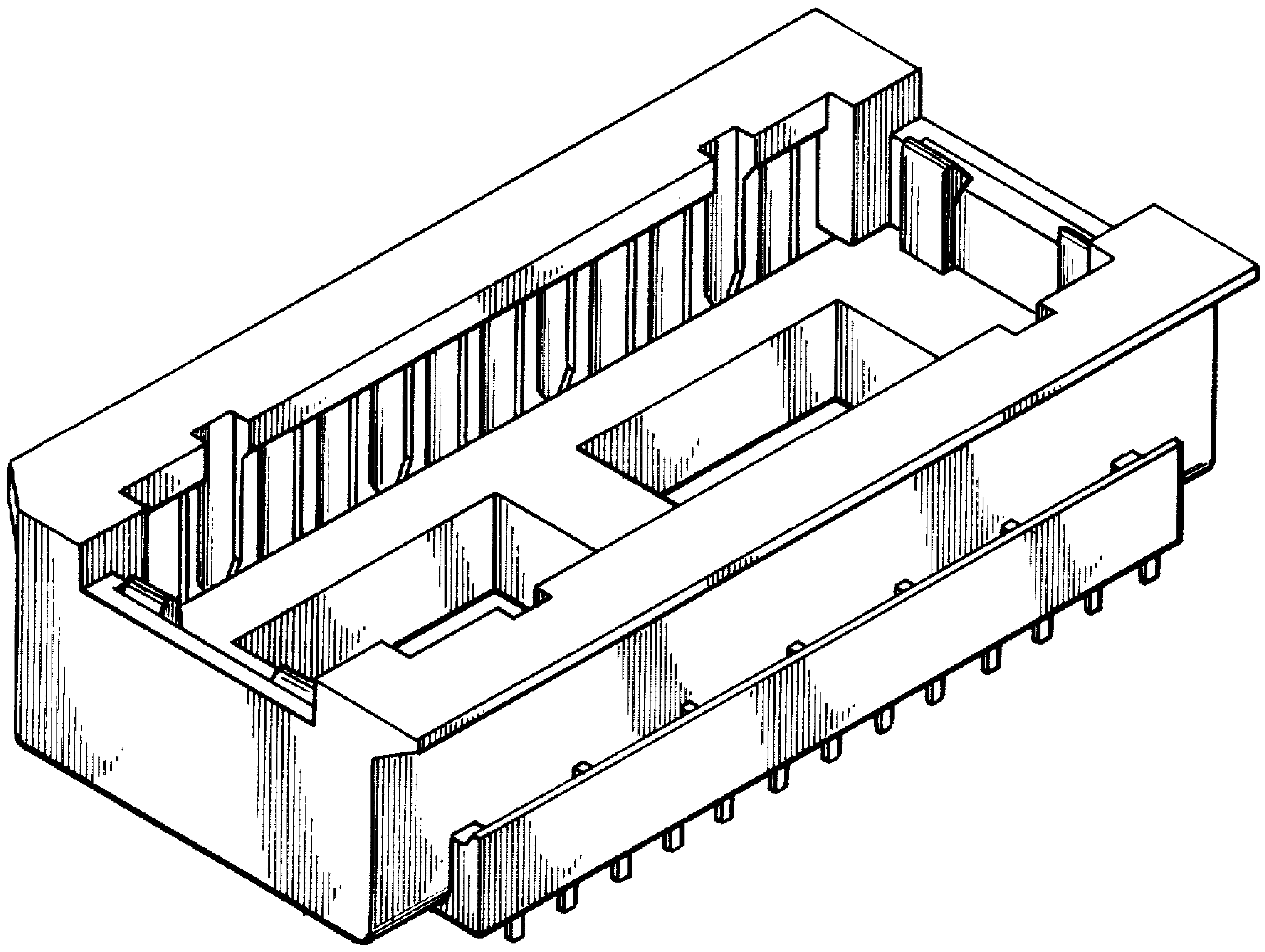
FIG. 4 is a right side elevational view thereof on a reduced scale.

FIG. 5 is a front elevational view thereof on a reduced scale.

FIG. 6 is a rear elevational view thereof on a reduced scale.

FIG. 7 is an isometric view thereof on a reduced scale looking generally downward.

FIG. 8 is an isometric view thereof on a reduced scale looking generally upward.



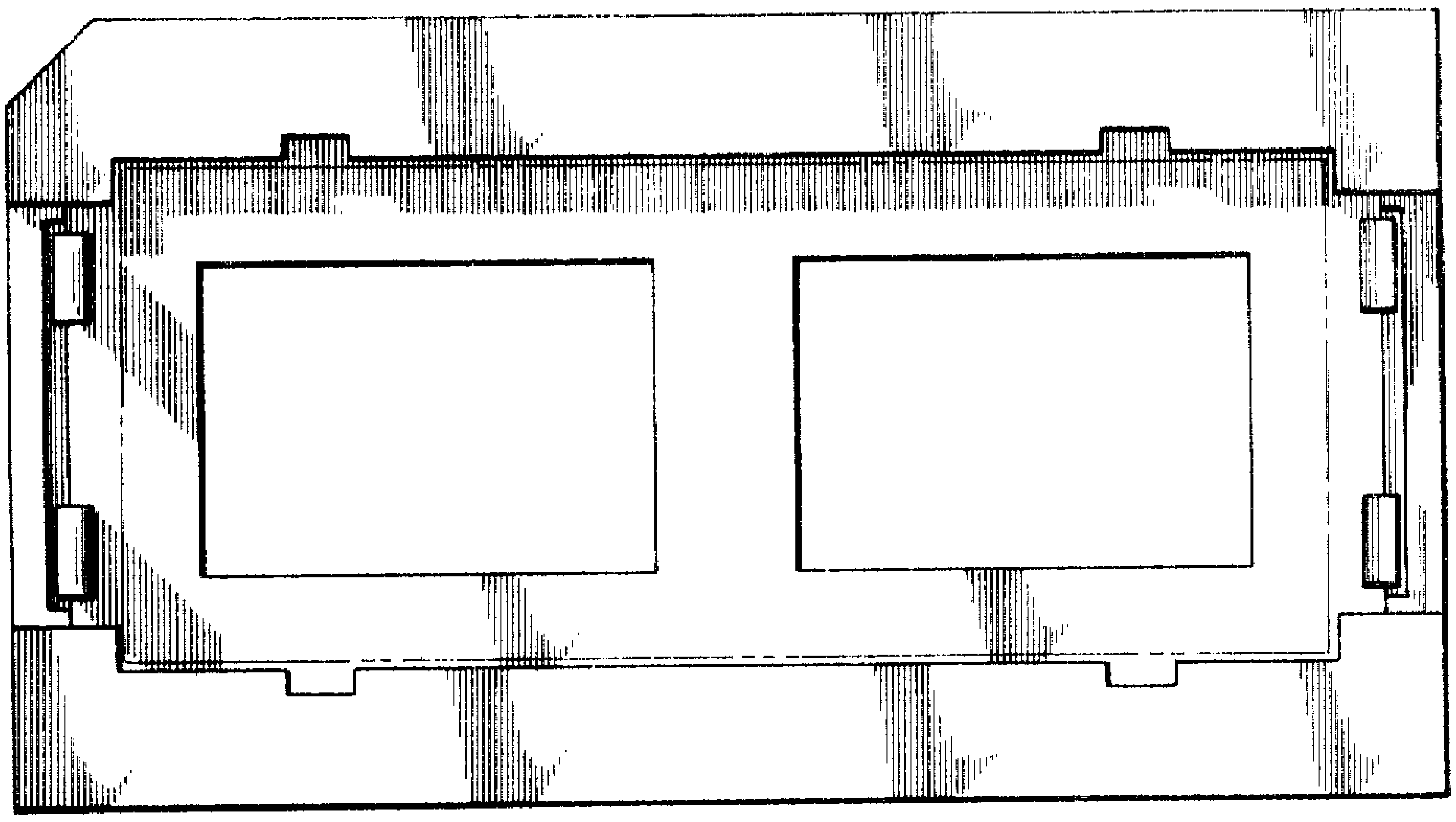


FIG. 1

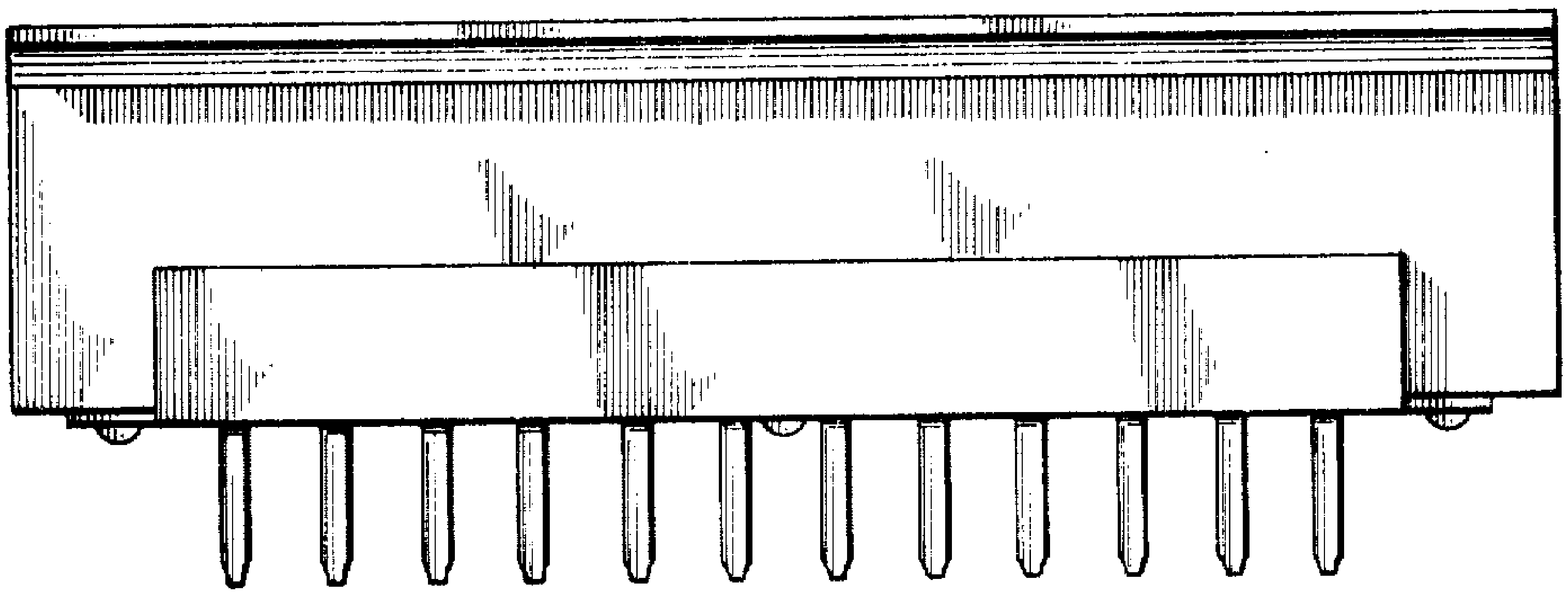


FIG. 2

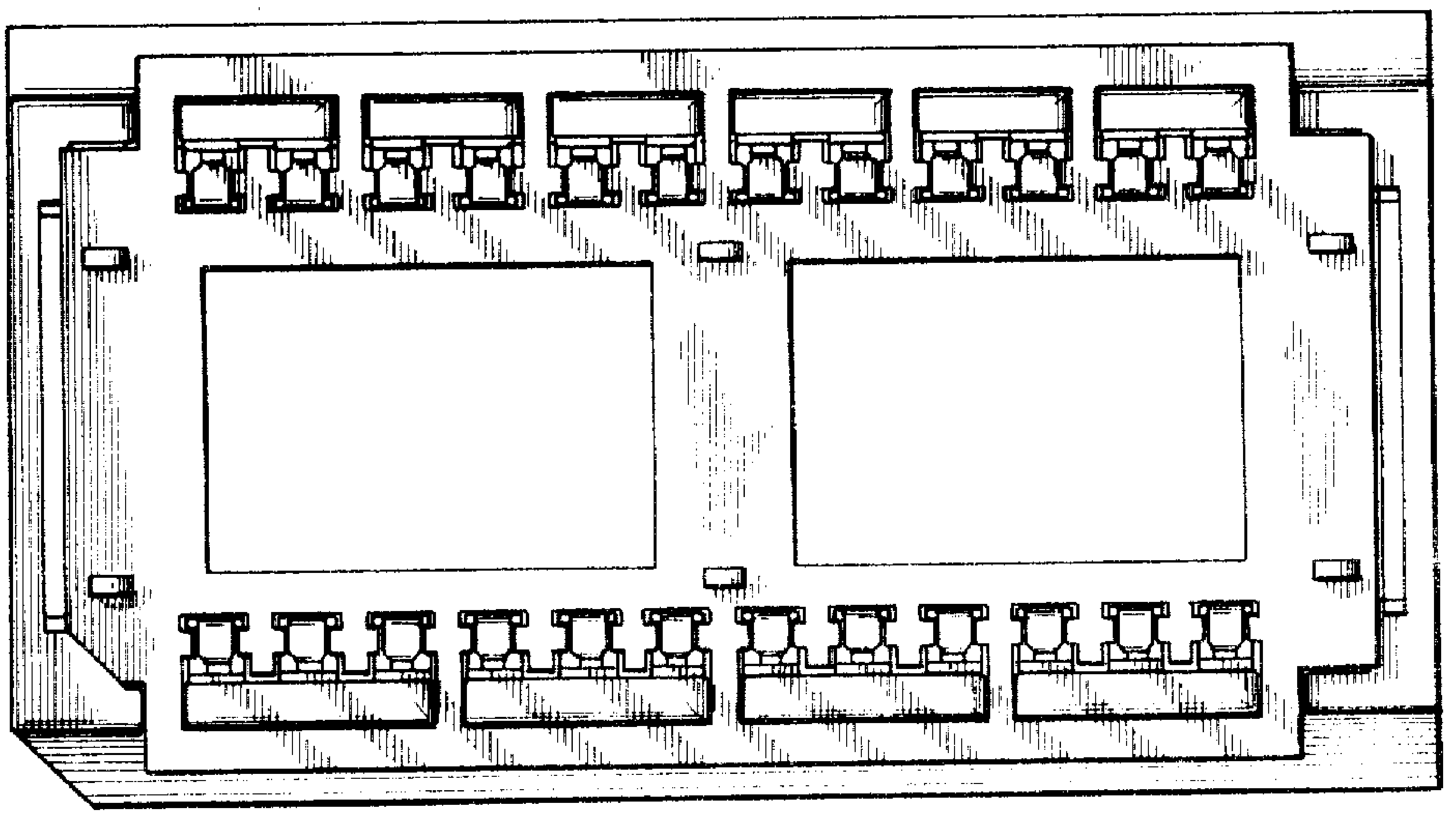


FIG. 3

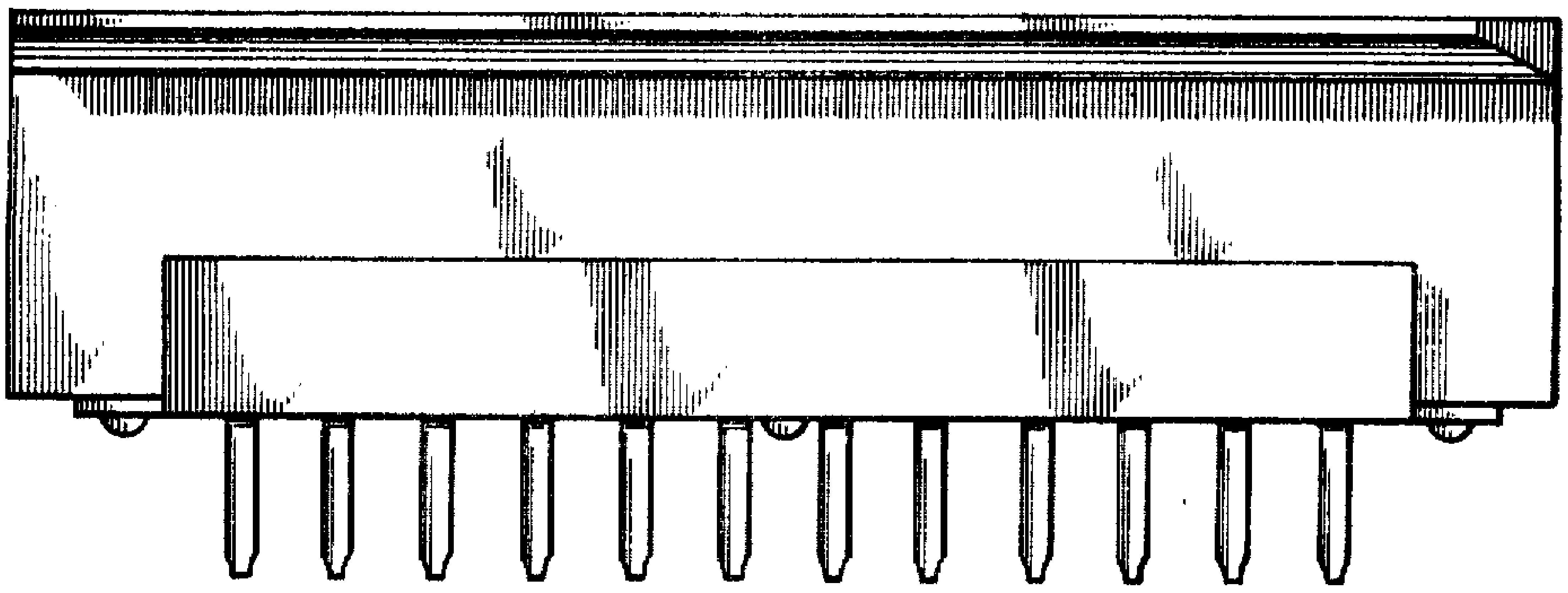


FIG. 4

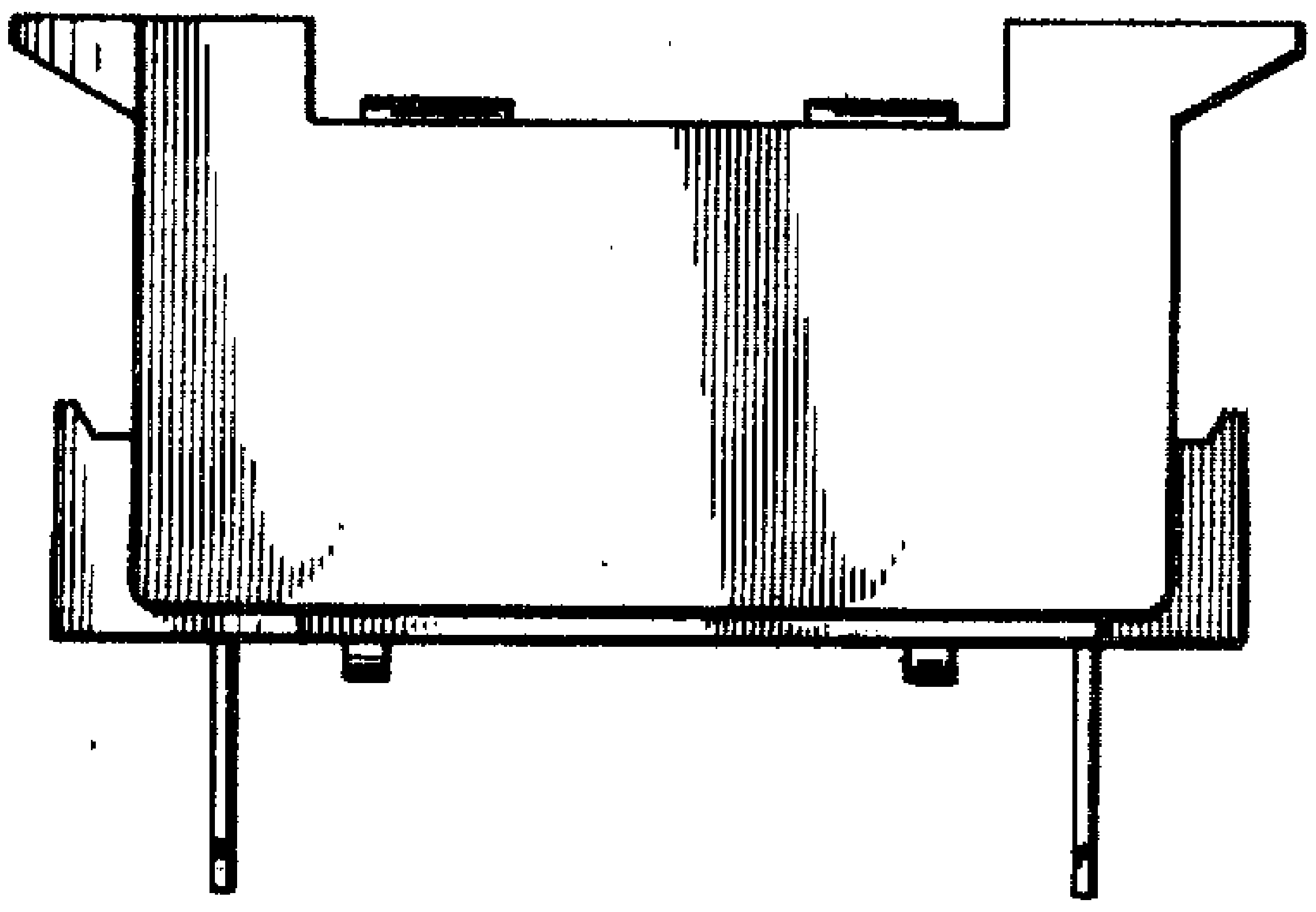


FIG. 5

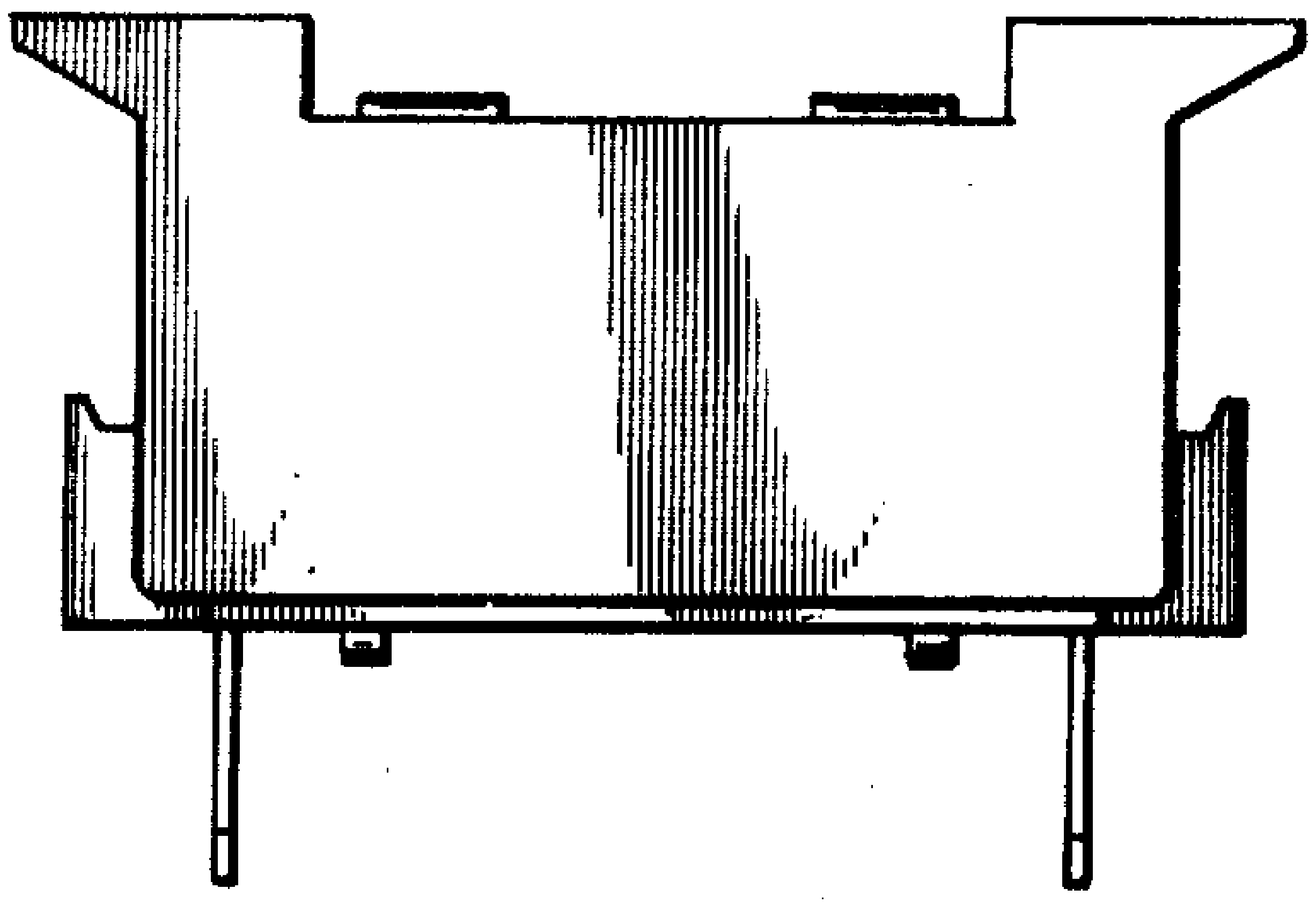


FIG. 6

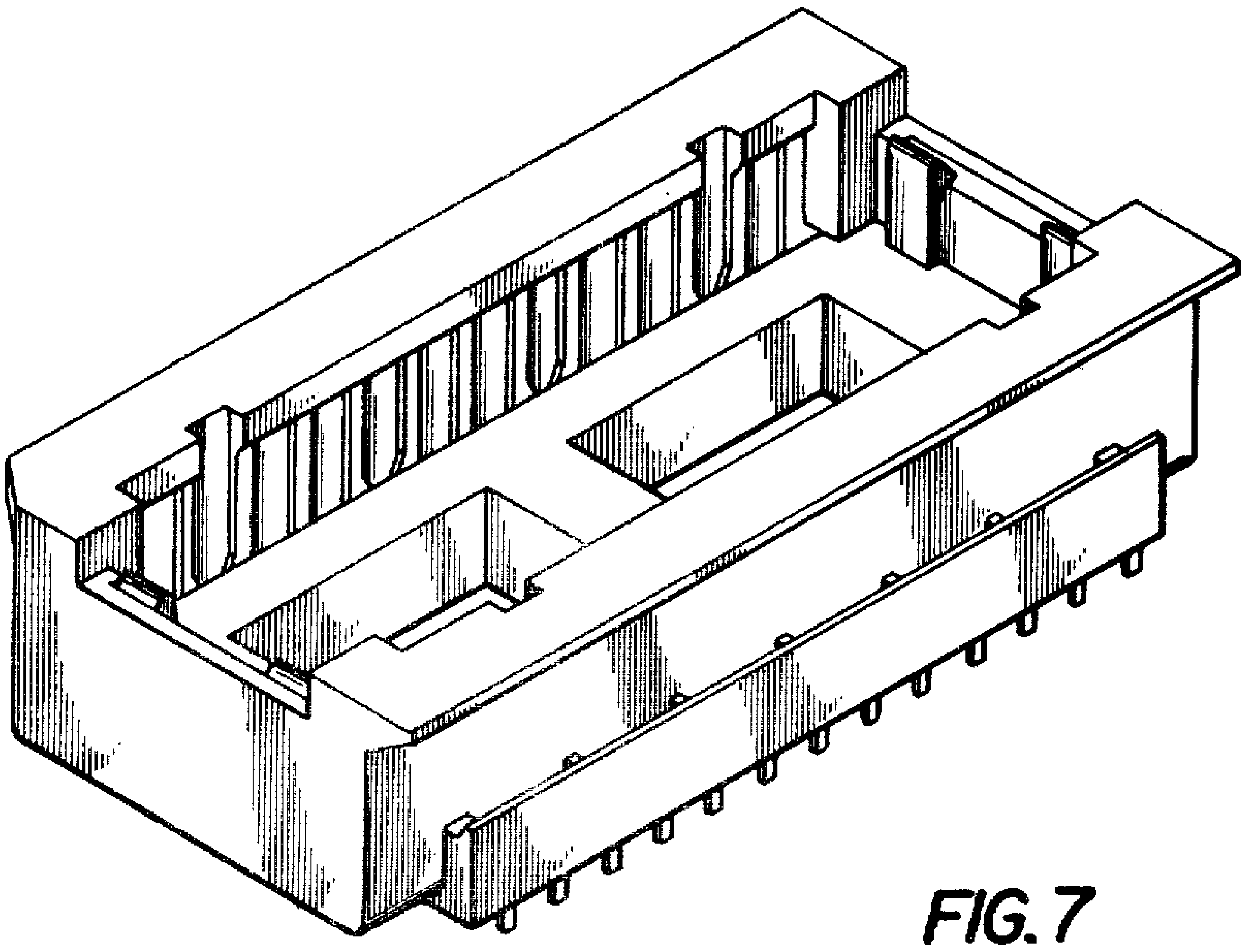


FIG. 7

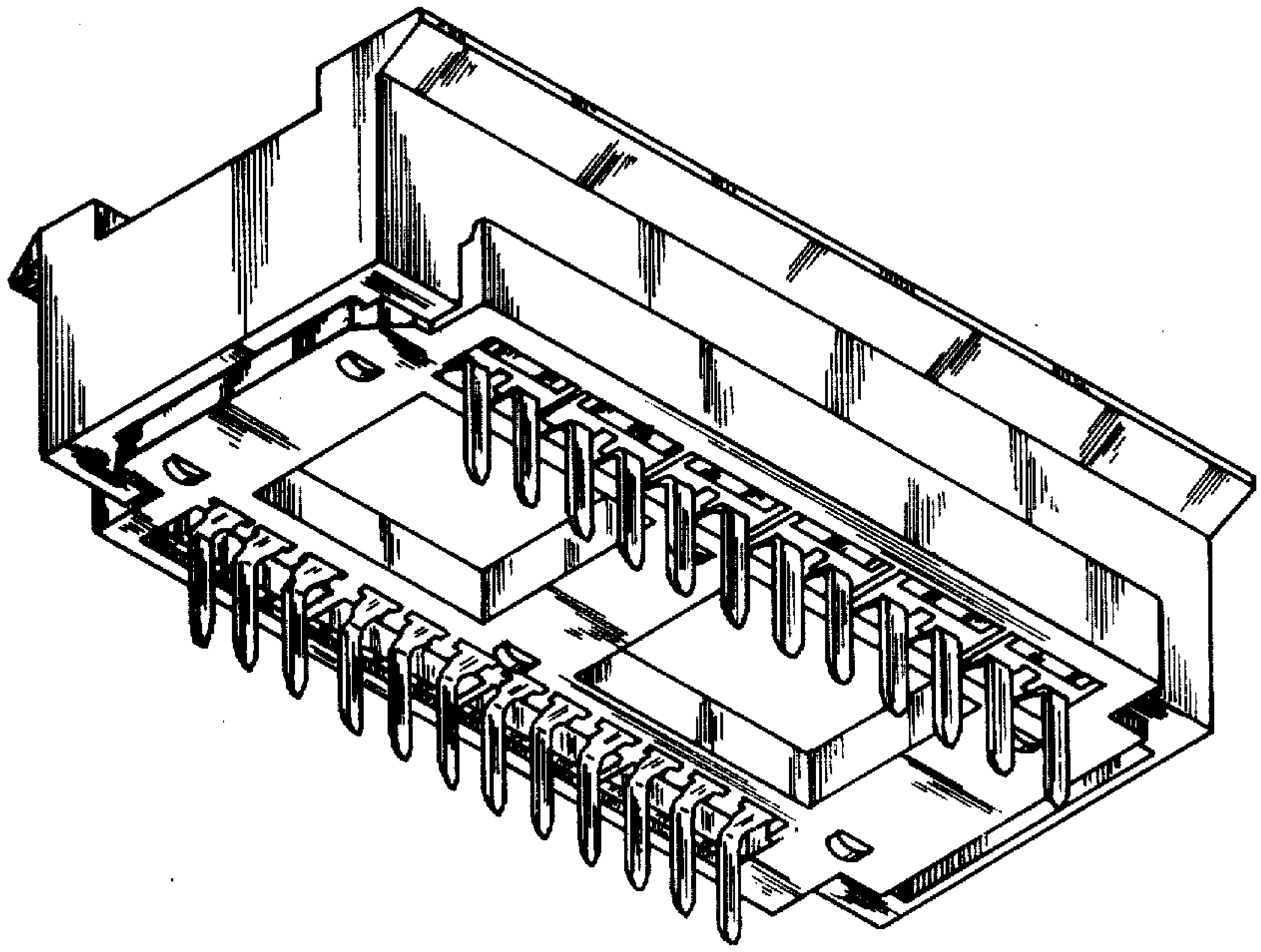


Fig. 8